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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	6000
Total RAM Bits	73728
Number of I/O	188
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp6c-3fn256i

Introduction

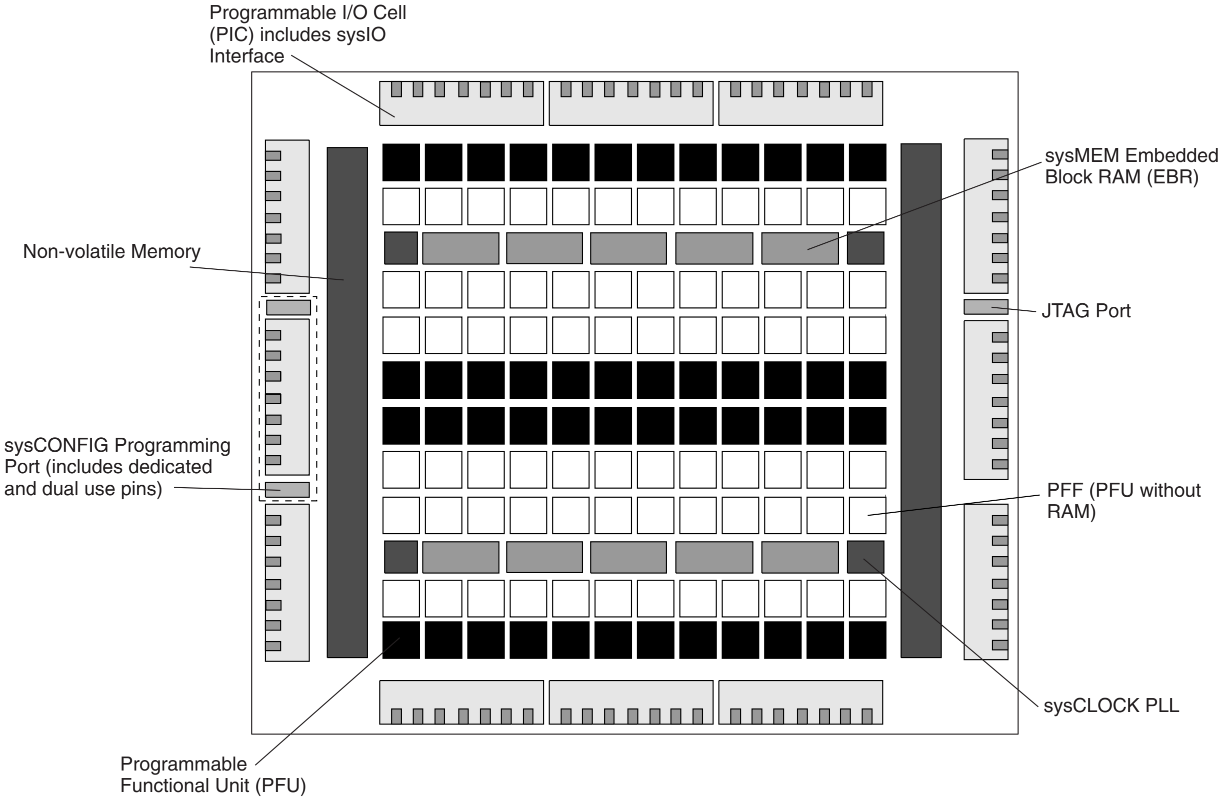
The LatticeXP family of FPGA devices combine logic gates, embedded memory and high performance I/Os in a single architecture that is both non-volatile and infinitely reconfigurable to support cost-effective system designs.

The re-programmable non-volatile technology used in the LatticeXP family is the next generation ispXP™ technology. With this technology, expensive external configuration memories are not required and designs are secured from unauthorized read-back. In addition, instant-on capability allows for easy interfacing in many applications.

The ispLEVER® design tool from Lattice allows large complex designs to be efficiently implemented using the LatticeXP family of FPGA devices. Synthesis library support for LatticeXP is available for popular logic synthesis tools. The ispLEVER tool uses the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the LatticeXP device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Lattice provides many pre-designed IP (Intellectual Property) ispLeverCORE™ modules for the LatticeXP family. By using these IPs as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

Figure 2-1. LatticeXP Top Level Block Diagram

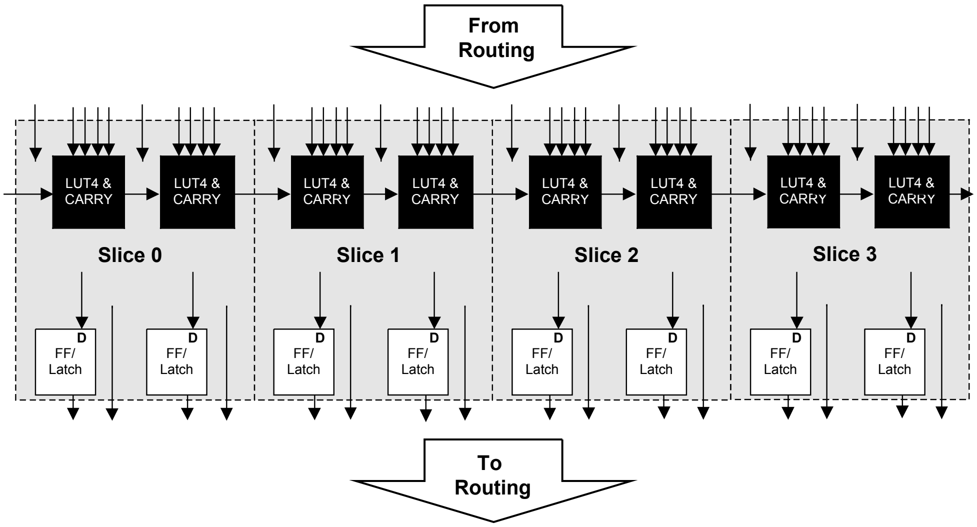


PFU and PFF Blocks

The core of the LatticeXP devices consists of PFU and PFF blocks. The PFUs can be programmed to perform Logic, Arithmetic, Distributed RAM and Distributed ROM functions. PFF blocks can be programmed to perform Logic, Arithmetic and ROM functions. Except where necessary, the remainder of the data sheet will use the term PFU to refer to both PFU and PFF blocks.

Each PFU block consists of four interconnected slices, numbered 0-3 as shown in Figure 2-2. All the interconnections to and from PFU blocks are from routing. There are 53 inputs and 25 outputs associated with each PFU block.

Figure 2-2. PFU Diagram



For more information on the PLL, please see details of additional technical documentation at the end of this data sheet.

Dynamic Clock Select (DCS)

The DCS is a global clock buffer with smart multiplexer functions. It takes two independent input clock sources and outputs a clock signal without any glitches or runt pulses. This is achieved irrespective of where the select signal is toggled. There are eight DCS blocks per device, located in pairs at the center of each side. Figure 2-12 illustrates the DCS Block Macro.

Figure 2-12. DCS Block Primitive

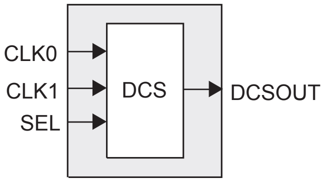
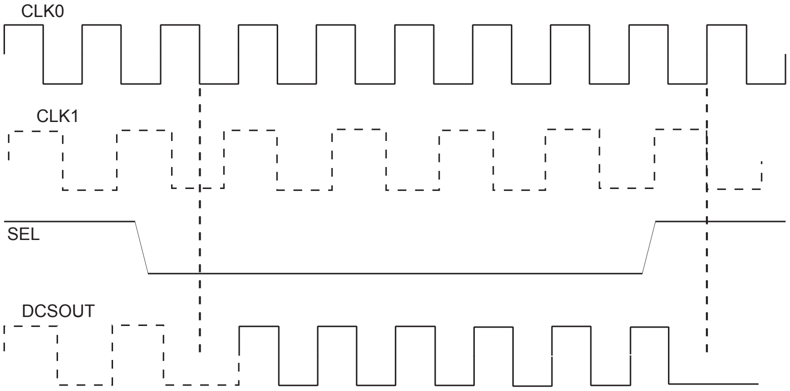


Figure 2-13 shows timing waveforms of the default DCS operating mode. The DCS block can be programmed to other modes. For more information on the DCS, please see details of additional technical documentation at the end of this data sheet.

Figure 2-13. DCS Waveforms



sysMEM Memory

The LatticeXP family of devices contain a number of sysMEM Embedded Block RAM (EBR). The EBR consists of a 9-Kbit RAM, with dedicated input and output registers.

sysMEM Memory Block

The sysMEM block can implement single port, dual port or pseudo dual port memories. Each block can be used in a variety of depths and widths as shown in Table 2-6.

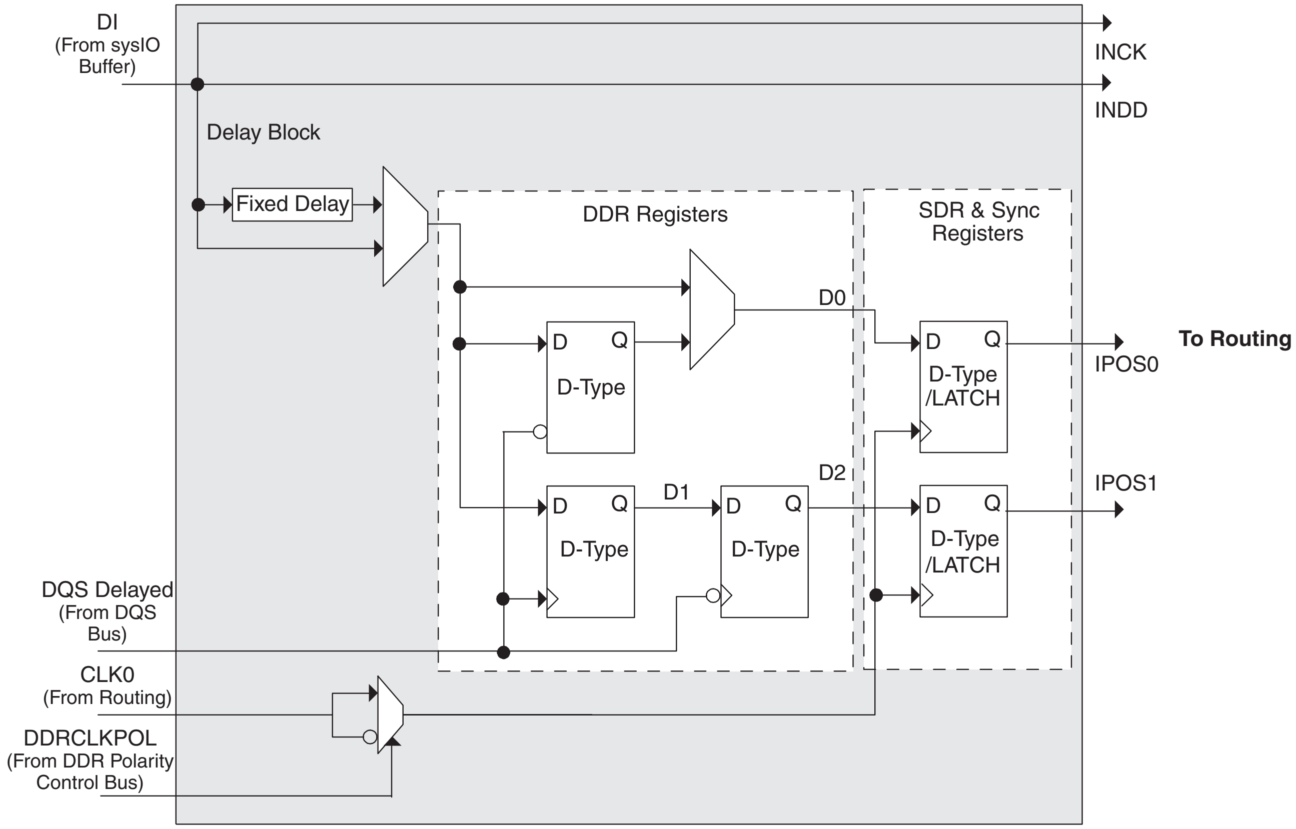
in selected blocks the input to the DQS delay block. If one of the bypass options is not chosen, the signal first passes through an optional delay block. This delay, if selected, ensures no positive input-register hold-time requirement when using a global clock.

The input block allows two modes of operation. In the single data rate (SDR) the data is registered, by one of the registers in the single data rate sync register block, with the system clock. In the DDR Mode two registers are used to sample the data on the positive and negative edges of the DQS signal creating two data streams, D0 and D2. These two data streams are synchronized with the system clock before entering the core. Further discussion on this topic is in the DDR Memory section of this data sheet.

Figure 2-21 shows the input register waveforms for DDR operation and Figure 2-22 shows the design tool primitives. The SDR/SYNC registers have reset and clock enable available.

The signal DDRCLKPOL controls the polarity of the clock used in the synchronization registers. It ensures adequate timing when data is transferred from the DQS to the system clock domain. For further discussion of this topic, see the DDR memory section of this data sheet.

Figure 2-20. Input Register Diagram



master serial clock is 2.5MHz. Table 2-10 lists all the available Master Serial Clock frequencies. When a different Master Serial Clock is selected during the design process, the following sequence takes place:

1. User selects a different Master Serial Clock frequency for configuration.
2. During configuration the device starts with the default (2.5MHz) Master Serial Clock frequency.
3. The clock configuration settings are contained in the early configuration bit stream.
4. The Master Serial Clock frequency changes to the selected frequency once the clock configuration bits are received.

For further information on the use of this oscillator for configuration, please see details of additional technical documentation at the end of this data sheet.

Table 2-10. Selectable Master Serial Clock (CCLK) Frequencies During Configuration

CCLK (MHz)	CCLK (MHz)	CCLK (MHz)
2.5[1]	13	45
4.3	15	51
5.4	20	55
6.9	26	60
8.1	30	130
9.2	34	—
10.0	41	—

1. Default

Density Shifting

The LatticeXP family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

sysIO Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL} (mA)	I_{OH} (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.8	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.5	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	8, 4	-8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2 (“C” Version)	-0.3	0.42	0.78	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2 (“E” Version)	-0.3	$0.35V_{CC}$	$0.65V_{CC}$	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.6	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5
SSTL3 class I	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.7	V_{CCIO} - 1.1	8	-8
SSTL3 class II	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.5	V_{CCIO} - 0.9	16	-16
SSTL2 class I	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.54	V_{CCIO} - 0.62	7.6	-7.6
SSTL2 class II	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.35	V_{CCIO} - 0.43	15.2	-15.2
SSTL18 class I	-0.3	V_{REF} - 0.125	V_{REF} + 0.125	3.6	0.4	V_{CCIO} - 0.4	6.7	-6.7
HSTL15 class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	8	-8
HSTL15 class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	24	-8
HSTL18 class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	9.6	-9.6
HSTL18 class II	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	16	-16
HSTL18 class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	24	-8

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed n * 8mA. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

LatticeXP External Switching Characteristics

Over Recommended Operating Conditions

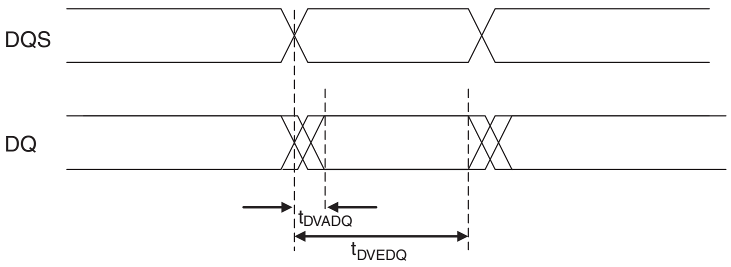
Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (Using Primary Clock without PLL)[1]									
t_{CO}	Clock to Output - PIO Output Register	LFXP3	—	5.12	—	6.12	—	7.43	ns
		LFXP6	—	5.30	—	6.34	—	7.69	ns
		LFXP10	—	5.52	—	6.60	—	8.00	ns
		LFXP15	—	5.72	—	6.84	—	8.29	ns
		LFXP20	—	5.97	—	7.14	—	8.65	ns
t_{SU}	Clock to Data Setup - PIO Input Register	LFXP3	-0.40	—	-0.28	—	-0.16	—	ns
		LFXP6	-0.33	—	-0.32	—	-0.30	—	ns
		LFXP10	-0.61	—	-0.71	—	-0.81	—	ns
		LFXP15	-0.71	—	-0.77	—	-0.87	—	ns
		LFXP20	-0.95	—	-1.14	—	-1.35	—	ns
t_{H}	Clock to Data Hold - PIO Input Register	LFXP3	2.10	—	2.50	—	2.98	—	ns
		LFXP6	2.28	—	2.72	—	3.24	—	ns
		LFXP10	3.02	—	3.51	—	3.71	—	ns
		LFXP15	2.70	—	3.22	—	3.85	—	ns
		LFXP20	2.95	—	3.52	—	4.21	—	ns
t_{SU_DEL}	Clock to Data Setup - PIO Input Register with Input Data Delay	LFXP3	2.38	—	2.49	—	2.66	—	ns
		LFXP6	2.92	—	3.18	—	3.42	—	ns
		LFXP10	2.72	—	2.75	—	2.84	—	ns
		LFXP15	2.99	—	3.13	—	3.18	—	ns
		LFXP20	4.47	—	4.56	—	4.80	—	ns
t_{H_DEL}	Clock to Data Hold - PIO Input Register with Input Data Delay	LFXP3	-0.70	—	-0.80	—	-0.92	—	ns
		LFXP6	-0.47	—	-0.38	—	-0.31	—	ns
		LFXP10	-0.60	—	-0.47	—	-0.32	—	ns
		LFXP15	-1.05	—	-0.98	—	-1.01	—	ns
		LFXP20	-0.80	—	-0.58	—	-0.31	—	ns
f_{MAX_IO}	Clock Frequency of I/O and PFU Register	All	—	400	—	360	—	320	MHz
DDR I/O Pin Parameters[2]									
t_{DVADQ}	Data Valid After DQS (DDR Read)	All	—	0.19	—	0.19	—	0.19	UI
t_{DVEDQ}	Data Hold After DQS (DDR Read)	All	0.67	—	0.67	—	0.67	—	UI
t_{DQVBS}	Data Valid Before DQS	All	0.20	—	0.20	—	0.20	—	UI
t_{DQVAS}	Data Valid After DQS	All	0.20	—	0.20	—	0.20	—	UI
f_{MAX_DDR}	DDR Clock Frequency	All	95	166	95	133	95	100	MHz
Primary and Secondary Clocks									
f_{MAX_PRI}	Frequency for Primary Clock Tree	All	—	450	—	412	—	375	MHz
t_{W_PRI}	Clock Pulse Width for Primary Clock	All	1.19	—	1.19	—	1.19	—	ns
t_{SKEW_PRI}	Primary Clock Skew within an I/O Bank	LFXP3/6/10/15	—	250	—	300	—	350	ps
		LFXP20	—	300	—	350	—	400	ps

1. General timing numbers based on LVCMOS 2.5, 12mA.
2. DDR timing numbers based on SSTL I/O.

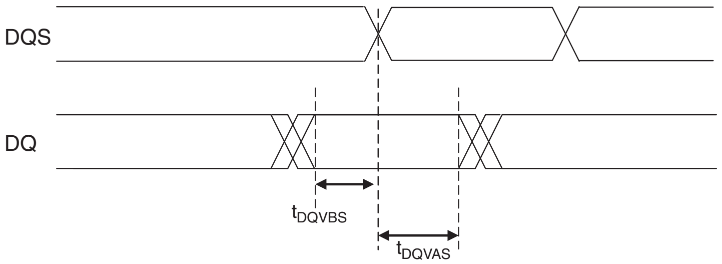
Timing v.F0.11

Figure 3-5. DDR Timings

DQ and DQS Read Timings



DQ and DQS Write Timings



LatticeXP Internal Timing Parameters[1]

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
PFU/PFF Logic Mode Timing								
t_{LUT4_PFU}	LUT4 Delay (A to D Inputs to F Output)	—	0.28	—	0.34	—	0.40	ns
t_{LUT6_PFU}	LUT6 Delay (A to D Inputs to OFX Output)	—	0.44	—	0.53	—	0.63	ns
t_{LSR_PFU}	Set/Reset to Output of PFU	—	0.90	—	1.08	—	1.29	ns
t_{SUM_PFU}	Clock to Mux (M0,M1) Input Setup Time	0.13	—	0.15	—	0.19	—	ns
t_{HM_PFU}	Clock to Mux (M0,M1) Input Hold Time	-0.04	—	-0.03	—	-0.03	—	ns
t_{SUD_PFU}	Clock to D Input Setup Time	0.13	—	0.16	—	0.19	—	ns
t_{HD_PFU}	Clock to D Input Hold Time	-0.03	—	-0.02	—	-0.02	—	ns
t_{CK2Q_PFU}	Clock to Q Delay, D-type Register Configuration	—	0.40	—	0.48	—	0.58	ns
t_{LE2Q_PFU}	Clock to Q Delay Latch Configuration	—	0.53	—	0.64	—	0.76	ns
t_{LD2Q_PFU}	D to Q Throughput Delay when Latch is Enabled	—	0.55	—	0.66	—	0.79	ns
PFU Dual Port Memory Mode Timing								
t_{CORAM_PFU}	Clock to Output	—	0.40	—	0.48	—	0.58	ns
t_{SUDATA_PFU}	Data Setup Time	-0.18	—	-0.14	—	-0.11	—	ns
t_{HDATA_PFU}	Data Hold Time	0.28	—	0.34	—	0.40	—	ns
t_{SUADDR_PFU}	Address Setup Time	-0.46	—	-0.37	—	-0.30	—	ns
t_{HADDR_PFU}	Address Hold Time	0.71	—	0.85	—	1.02	—	ns
t_{SUWREN_PFU}	Write/Read Enable Setup Time	-0.22	—	-0.17	—	-0.14	—	ns
t_{HWREN_PFU}	Write/Read Enable Hold Time	0.33	—	0.40	—	0.48	—	ns
PIC Timing								
PIO Input/Output Buffer Timing								
t_{IN_PIO}	Input Buffer Delay	—	0.62	—	0.72	—	0.85	ns
t_{OUT_PIO}	Output Buffer Delay	—	2.12	—	2.54	—	3.05	ns
IOLOGIC Input/Output Timing								
t_{SUI_PIO}	Input Register Setup Time (Data Before Clock)	1.35	—	1.83	—	2.37	—	ns
t_{HI_PIO}	Input Register Hold Time (Data After Clock)	0.05	—	0.05	—	0.05	—	ns
t_{COO_PIO}	Output Register Clock to Output Delay	—	0.36	—	0.44	—	0.52	ns
t_{SUCE_PIO}	Input Register Clock Enable Setup Time	-0.09	—	-0.07	—	-0.06	—	ns
t_{HCE_PIO}	Input Register Clock Enable Hold Time	0.13	—	0.16	—	0.19	—	ns
t_{SULSR_PIO}	Set/Reset Setup Time	0.19	—	0.23	—	0.28	—	ns
t_{HLSR_PIO}	Set/Reset Hold Time	-0.14	—	-0.11	—	-0.09	—	ns
EBR Timing								
t_{CO_EBR}	Clock to Output from Address or Data	—	4.01	—	4.81	—	5.78	ns
t_{COO_EBR}	Clock to Output from EBR Output Register	—	0.81	—	0.97	—	1.17	ns
t_{SUDATA_EBR}	Setup Data to EBR Memory	-0.26	—	-0.21	—	-0.17	—	ns
t_{HDATA_EBR}	Hold Data to EBR Memory	0.41	—	0.49	—	0.59	—	ns
t_{SUADDR_EBR}	Setup Address to EBR Memory	-0.26	—	-0.21	—	-0.17	—	ns
t_{HADDR_EBR}	Hold Address to EBR Memory	0.41	—	0.49	—	0.59	—	ns
t_{SUWREN_EBR}	Setup Write/Read Enable to EBR Memory	-0.17	—	-0.13	—	-0.11	—	ns
t_{HWREN_EBR}	Hold Write/Read Enable to EBR Memory	0.26	—	0.31	—	0.37	—	ns
t_{SUCE_EBR}	Clock Enable Setup Time to EBR Output Register	0.19	—	0.23	—	0.28	—	ns
t_{HCE_EBR}	Clock Enable Hold Time to EBR Output Register	-0.13	—	-0.10	—	-0.08	—	ns

LatticeXP Family Timing Adders[1]

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25E	LVDS 2.5 Emulated	0.5	0.5	0.5	ns
LVDS25	LVDS	0.4	0.4	0.4	ns
BLVDS25	BLVDS	0.5	0.5	0.5	ns
LVPECL33	LVPECL	0.6	0.6	0.6	ns
HSTL18_I	HSTL_18 class I	0.4	0.4	0.4	ns
HSTL18_II	HSTL_18 class II	0.4	0.4	0.4	ns
HSTL18_III	HSTL_18 class III	0.4	0.4	0.4	ns
HSTL18D_I	Differential HSTL 18 class I	0.4	0.4	0.4	ns
HSTL18D_II	Differential HSTL 18 class II	0.4	0.4	0.4	ns
HSTL18D_III	Differential HSTL 18 class III	0.4	0.4	0.4	ns
HSTL15_I	HSTL_15 class I	0.5	0.5	0.5	ns
HSTL15_III	HSTL_15 class III	0.5	0.5	0.5	ns
HSTL15D_I	Differential HSTL 15 class I	0.5	0.5	0.5	ns
HSTL15D_III	Differential HSTL 15 class III	0.5	0.5	0.5	ns
SSTL33_I	SSTL_3 class I	0.6	0.6	0.6	ns
SSTL33_II	SSTL_3 class II	0.6	0.6	0.6	ns
SSTL33D_I	Differential SSTL_3 class I	0.6	0.6	0.6	ns
SSTL33D_II	Differential SSTL_3 class II	0.6	0.6	0.6	ns
SSTL25_I	SSTL_2 class I	0.5	0.5	0.5	ns
SSTL25_II	SSTL_2 class II	0.5	0.5	0.5	ns
SSTL25D_I	Differential SSTL_2 class I	0.5	0.5	0.5	ns
SSTL25D_II	Differential SSTL_2 class II	0.5	0.5	0.5	ns
SSTL18_I	SSTL_18 class I	0.5	0.5	0.5	ns
SSTL18D_I	Differential SSTL_18 class I	0.5	0.5	0.5	ns
LVTTL33	LVTTL	0.2	0.2	0.2	ns
LVCMOS33	LVCMOS 3.3	0.2	0.2	0.2	ns
LVCMOS25	LVCMOS 2.5	0.0	0.0	0.0	ns
LVCMOS18	LVCMOS 1.8	0.1	0.1	0.1	ns
LVCMOS15	LVCMOS 1.5	0.1	0.1	0.1	ns
LVCMOS12	LVCMOS 1.2	0.1	0.1	0.1	ns
PCI33	PCI	0.2	0.2	0.2	ns
Output Adjusters					
LVDS25E	LVDS 2.5 Emulated	0.3	0.3	0.3	ns
LVDS25	LVDS 2.5	0.3	0.3	0.3	ns
BLVDS25	BLVDS 2.5	0.3	0.3	0.3	ns
LVPECL33	LVPECL 3.3	0.1	0.1	0.1	ns
HSTL18_I	HSTL_18 class I	0.1	0.1	0.1	ns
HSTL18_II	HSTL_18 class II	0.1	0.1	0.1	ns
HSTL18_III	HSTL_18 class III	0.2	0.2	0.2	ns
HSTL18D_I	Differential HSTL 18 class I	0.1	0.1	0.1	ns
HSTL18D_II	Differential HSTL 18 class II	-0.1	-0.1	-0.1	ns
HSTL18D_III	Differential HSTL 18 class III	0.2	0.2	0.2	ns

Pin Information Summary[1] (Cont.)

Pin Type		XP10		XP15			XP20		
		256 fpBGA	388 fpBGA	256 fpBGA	388 fpBGA	484 fpBGA	256 fpBGA	388 fpBGA	484 fpBGA
Single Ended User I/O		188	244	188	268	300	188	268	340
Differential Pair User I/O[2]		76	104	76	112	128	76	112	144
Configuration	Dedicated	11	11	11	11	11	11	11	11
	Muxed	14	14	14	14	14	14	14	14
TAP		5	5	5	5	5	5	5	5
Dedicated (total without supplies)		6	6	6	6	6	6	6	6
V_{CC}		8	14	8	14	28	8	14	28
V_{CCAUX}		4	4	4	4	12	4	4	12
V_{CCPLL}		2	2	2	2	2	2	2	2
V_{CCIO}	Bank0	2	5	2	5	4	2	5	4
	Bank1	2	5	2	5	4	2	5	4
	Bank2	2	4	2	4	4	2	4	4
	Bank3	2	4	2	4	4	2	4	4
	Bank4	2	5	2	5	4	2	5	4
	Bank5	2	5	2	5	4	2	5	4
	Bank6	2	4	2	4	4	2	4	4
	Bank7	2	4	2	4	4	2	4	4
GND		24	50	24	50	56	24	50	56
GND_{PLL}		2	2	2	2	2	2	2	2
NC		0	24	0	0	40	0	0	0
Single Ended/ Differential I/O per Bank[2]	Bank0	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank1	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank2	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
	Bank3	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
	Bank4	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank5	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank6	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
	Bank7	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
V_{CCJ}		1	1	1	1	1	1	1	1

1. During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.
2. The differential I/O per bank includes both dedicated LVDS and emulated LVDS pin pairs. Please see the Logic Signal Connections table for more information.

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

	LFXP10				LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
Y10	PB11B	5	C	-	PB16B	5	C	-	PB20B	5	C	-
AA7	PB12A	5	T	-	PB17A	5	T	-	PB21A	5	T	-
AB7	PB12B	5	C	VREF2_5	PB17B	5	C	VREF2_5	PB21B	5	C	VREF2_5
Y7	PB13A	5	T	-	PB18A	5	T	-	PB22A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-	GNDIO5	5	-	-
AA8	PB13B	5	C	-	PB18B	5	C	-	PB22B	5	C	-
AB8	PB14A	5	T	-	PB19A	5	T	-	PB23A	5	T	-
Y8	PB14B	5	C	-	PB19B	5	C	-	PB23B	5	C	-
AB9	PB15A	5	T	-	PB20A	5	T	-	PB24A	5	T	-
AA9	PB15B	5	C	-	PB20B	5	C	-	PB24B	5	C	-
W10	PB16A	5	-	-	PB21A	5	-	-	PB25A	5	-	-
W11	PB17B	5	-	-	PB22B	5	-	-	PB26B	5	-	-
AB10	PB18A	5	T	DQS	PB23A	5	T	DQS	PB27A	5	T	DQS
AA10	PB18B	5	C	-	PB23B	5	C	-	PB27B	5	C	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-	GNDIO5	5	-	-
AA11	PB19A	5	T	-	PB24A	5	T	-	PB28A	5	T	-
AB11	PB19B	5	C	-	PB24B	5	C	-	PB28B	5	C	-
Y11	PB20A	5	T	-	PB25A	5	T	-	PB29A	5	T	-
Y12	PB20B	5	C	-	PB25B	5	C	-	PB29B	5	C	-
AB12	PB21A	4	T	-	PB26A	4	T	-	PB30A	4	T	-
AA12	PB21B	4	C	-	PB26B	4	C	-	PB30B	4	C	-
AB13	PB22A	4	T	PCLKT4_0	PB27A	4	T	PCLKT4_0	PB31A	4	T	PCLKT4_0
AA13	PB22B	4	C	PCLKC4_0	PB27B	4	C	PCLKC4_0	PB31B	4	C	PCLKC4_0
-	GNDIO4	4	-	-	GNDIO4	4	-	-	GNDIO4	4	-	-
AA14	PB23A	4	T	-	PB28A	4	T	-	PB32A	4	T	-
AB14	PB23B	4	C	-	PB28B	4	C	-	PB32B	4	C	-
W12	PB24A	4	-	-	PB29A	4	-	-	PB33A	4	-	-
W13	PB25B	4	-	-	PB30B	4	-	-	PB34B	4	-	-
AA15	PB26A	4	T	DQS	PB31A	4	T	DQS	PB35A	4	T	DQS
AB15	PB26B	4	C	VREF1_4	PB31B	4	C	VREF1_4	PB35B	4	C	VREF1_4
AA16	PB27A	4	T	-	PB32A	4	T	-	PB36A	4	T	-
AB16	PB27B	4	C	-	PB32B	4	C	-	PB36B	4	C	-
Y17	PB28A	4	T	-	PB33A	4	T	-	PB37A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-	GNDIO4	4	-	-
AA17	PB28B	4	C	-	PB33B	4	C	-	PB37B	4	C	-
Y13	PB29A	4	T	-	PB34A	4	T	-	PB38A	4	T	-
Y14	PB29B	4	C	-	PB34B	4	C	-	PB38B	4	C	-
AB17	PB30A	4	T	-	PB35A	4	T	-	PB39A	4	T	-
Y18	PB30B	4	C	-	PB35B	4	C	-	PB39B	4	C	-
AA18	PB31A	4	T	VREF2_4	PB36A	4	T	VREF2_4	PB40A	4	T	VREF2_4
AB18	PB31B	4	C	-	PB36B	4	C	-	PB40B	4	C	-
Y19	PB32A	4	-	-	PB37A	4	-	-	PB41A	4	-	-
AB19	PB33B	4	-	-	PB38B	4	-	-	PB42B	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-	GNDIO4	4	-	-
AA19	PB34A	4	T	DQS	PB39A	4	T	DQS	PB43A	4	T	DQS
Y20	PB34B	4	C	-	PB39B	4	C	-	PB43B	4	C	-
W14	PB35A	4	T	-	PB40A	4	T	-	PB44A	4	T	-
W15	PB35B	4	C	-	PB40B	4	C	-	PB44B	4	C	-
AB20	PB36A	4	T	-	PB41A	4	T	-	PB45A	4	T	-

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

	LFXP10				LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
AA20	PB36B	4	C	-	PB41B	4	C	-	PB45B	4	C	-
AB21	PB37A	4	T	-	PB42A	4	T	-	PB46A	4	T	-
AA21	PB37B	4	C	-	PB42B	4	C	-	PB46B	4	C	-
AA22	PB38A	4	T	-	PB43A	4	T	-	PB47A	4	T	-
Y21	PB38B	4	C	-	PB43B	4	C	-	PB47B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-	GNDIO4	4	-	-
W16	PB39A	4	-	-	PB44A	4	T	-	PB48A	4	T	-
W17	-	-	-	-	PB44B	4	C	-	PB48B	4	C	-
Y15	-	-	-	-	PB45A	4	-	-	PB49A	4	-	-
Y16	-	-	-	-	PB46B	4	-	-	PB50B	4	-	-
W19	-	-	-	-	PB47A	4	T	DQS	PB51A	4	T	DQS
W18	-	-	-	-	PB47B	4	C	-	PB51B	4	C	-
W20	-	-	-	-	PB48A	4	-	-	PB52A	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-	GNDIO4	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-	GNDIO4	4	-	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-	GNDIO3	3	-	-
T20	PR35B	3	C[3]	-	PR39B	3	C[3]	-	PR43B	3	C[3]	-
T19	PR35A	3	T[3]	-	PR39A	3	T[3]	-	PR43A	3	T[3]	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-	GNDIO3	3	-	-
U19	PR34B	3	C	RLM0_PLLC_FB_A	PR38B	3	C	RLM0_PLLC_FB_A	PR42B	3	C	RLM0_PLLC_FB_A
U20	PR34A	3	T	RLM0_PLLT_FB_A	PR38A	3	T	RLM0_PLLT_FB_A	PR42A	3	T	RLM0_PLLT_FB_A
V19	PR33B	3	C[3]	-	PR37B	3	C[3]	-	PR41B	3	C[3]	-
V20	PR33A	3	T[3]	DQS	PR37A	3	T[3]	DQS	PR41A	3	T[3]	DQS
R19	PR32B	3	-	-	PR36B	3	-	-	PR40B	3	-	-
R20	PR31A	3	-	VREF1_3	PR35A	3	-	VREF1_3	PR39A	3	-	VREF1_3
W21	PR30B	3	C[3]	-	PR34B	3	C[3]	-	PR38B	3	C[3]	-
Y22	PR30A	3	T[3]	-	PR34A	3	T[3]	-	PR38A	3	T[3]	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-	GNDIO3	3	-	-
P19	PR29B	3	C	-	PR33B	3	C	-	PR37B	3	C	-
P20	PR29A	3	T	-	PR33A	3	T	-	PR37A	3	T	-
V21	PR28B	3	C[3]	-	PR32B	3	C[3]	-	PR36B	3	C[3]	-
W22	PR28A	3	T[3]	-	PR32A	3	T[3]	-	PR36A	3	T[3]	-
U21	PR26B	3	C[3]	-	PR30B	3	C[3]	-	PR34B	3	C[3]	-
V22	PR26A	3	T[3]	-	PR30A	3	T[3]	-	PR34A	3	T[3]	-
T21	PR25B	3	C	RLM0_PLLC_IN_A	PR29B	3	C	RLM0_PLLC_IN_A	PR33B	3	C	RLM0_PLLC_IN_A
U22	PR25A	3	T	RLM0_PLLT_IN_A	PR29A	3	T	RLM0_PLLT_IN_A	PR33A	3	T	RLM0_PLLT_IN_A
-	GNDIO3	3	-	-	GNDIO3	3	-	-	GNDIO3	3	-	-
R21	PR24B	3	C[3]	-	PR28B	3	C[3]	-	PR32B	3	C[3]	-
T22	PR24A	3	T[3]	DQS	PR28A	3	T[3]	DQS	PR32A	3	T[3]	DQS
N19	PR23B	3	-	-	PR27B	3	-	-	PR31B	3	-	-
N20	PR22A	3	-	VREF2_3	PR26A	3	-	VREF2_3	PR30A	3	-	VREF2_3
R22	PR21B	3	C[3]	-	PR25B	3	C[3]	-	PR29B	3	C[3]	-
P22	PR21A	3	T[3]	-	PR25A	3	T[3]	-	PR29A	3	T[3]	-
P21	PR20B	3	C	-	PR24B	3	C	-	PR28B	3	C	-
N21	PR20A	3	T	-	PR24A	3	T	-	PR28A	3	T	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-	GNDIO3	3	-	-
M20	PR19B	3	C[3]	-	PR23B	3	C[3]	-	PR27B	3	C[3]	-
M19	PR19A	3	T[3]	-	PR23A	3	T[3]	-	PR27A	3	T[3]	-
N22	GNDP1	-	-	-	GNDP1	-	-	-	GNDP1	-	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
B3	PT8B	0	C	-	PT12B	0	C	-
A3	PT8A	0	T	-	PT12A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
D7	PT7B	0	C	-	PT11B	0	C	-
C7	PT7A	0	T	DQS	PT11A	0	T	DQS
B2	PT6B	0	-	-	PT10B	0	-	-
C2	PT5A	0	-	-	PT9A	0	-	-
C3	PT4B	0	C	-	PT8B	0	C	-
D3	PT4A	0	T	-	PT8A	0	T	-
F7	PT3B	0	C	-	PT7B	0	C	-
E7	PT3A	0	T	-	PT7A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
C6	-	-	-	-	PT6B	0	C	-
D6	-	-	-	-	PT6A	0	T	-
C5	-	-	-	-	PT5B	0	C	-
C4	-	-	-	-	PT5A	0	T	-
F6	-	-	-	-	PT4B	0	C	-
E6	-	-	-	-	PT4A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
E4	-	-	-	-	PT3B	0	-	-
E5	CFG0	0	-	-	CFG0	0	-	-
D4	CFG1	0	-	-	CFG1	0	-	-
D5	DONE	0	-	-	DONE	0	-	-
A1	GND	-	-	-	GND	-	-	-
A2	GND	-	-	-	GND	-	-	-
A21	GND	-	-	-	GND	-	-	-
A22	GND	-	-	-	GND	-	-	-
AA1	GND	-	-	-	GND	-	-	-
AA22	GND	-	-	-	GND	-	-	-
AB1	GND	-	-	-	GND	-	-	-
AB2	GND	-	-	-	GND	-	-	-
AB21	GND	-	-	-	GND	-	-	-
AB22	GND	-	-	-	GND	-	-	-
B1	GND	-	-	-	GND	-	-	-
B22	GND	-	-	-	GND	-	-	-
H14	GND	-	-	-	GND	-	-	-
H9	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-
J11	GND	-	-	-	GND	-	-	-
J12	GND	-	-	-	GND	-	-	-
J13	GND	-	-	-	GND	-	-	-
J14	GND	-	-	-	GND	-	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
G9	VCC	-	-	-	VCC	-	-	-
H15	VCC	-	-	-	VCC	-	-	-
H8	VCC	-	-	-	VCC	-	-	-
J16	VCC	-	-	-	VCC	-	-	-
J7	VCC	-	-	-	VCC	-	-	-
K16	VCC	-	-	-	VCC	-	-	-
K17	VCC	-	-	-	VCC	-	-	-
K6	VCC	-	-	-	VCC	-	-	-
K7	VCC	-	-	-	VCC	-	-	-
N16	VCC	-	-	-	VCC	-	-	-
N17	VCC	-	-	-	VCC	-	-	-
N6	VCC	-	-	-	VCC	-	-	-
N7	VCC	-	-	-	VCC	-	-	-
P16	VCC	-	-	-	VCC	-	-	-
P7	VCC	-	-	-	VCC	-	-	-
R15	VCC	-	-	-	VCC	-	-	-
R8	VCC	-	-	-	VCC	-	-	-
T10	VCC	-	-	-	VCC	-	-	-
T13	VCC	-	-	-	VCC	-	-	-
T14	VCC	-	-	-	VCC	-	-	-
T9	VCC	-	-	-	VCC	-	-	-
U10	VCC	-	-	-	VCC	-	-	-
U13	VCC	-	-	-	VCC	-	-	-
G15	VCCAUX	-	-	-	VCCAUX	-	-	-
G16	VCCAUX	-	-	-	VCCAUX	-	-	-
G7	VCCAUX	-	-	-	VCCAUX	-	-	-
G8	VCCAUX	-	-	-	VCCAUX	-	-	-
H16	VCCAUX	-	-	-	VCCAUX	-	-	-
H7	VCCAUX	-	-	-	VCCAUX	-	-	-
R16	VCCAUX	-	-	-	VCCAUX	-	-	-
R7	VCCAUX	-	-	-	VCCAUX	-	-	-
T15	VCCAUX	-	-	-	VCCAUX	-	-	-
T16	VCCAUX	-	-	-	VCCAUX	-	-	-
T7	VCCAUX	-	-	-	VCCAUX	-	-	-
T8	VCCAUX	-	-	-	VCCAUX	-	-	-
F11	VCCIO0	0	-	-	VCCIO0	0	-	-
G11	VCCIO0	0	-	-	VCCIO0	0	-	-
H10	VCCIO0	0	-	-	VCCIO0	0	-	-
H11	VCCIO0	0	-	-	VCCIO0	0	-	-
F12	VCCIO1	1	-	-	VCCIO1	1	-	-
G12	VCCIO1	1	-	-	VCCIO1	1	-	-
H12	VCCIO1	1	-	-	VCCIO1	1	-	-

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1052 - Power Estimation and Management for LatticeECP/EC and LatticeXP Devices
- Power Calculator tool included with Lattice’s ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

LatticeXP Family Data Sheet
Ordering Information

December 2005 **Data Sheet DS1001**

Part Number Description

LFXP XX X – X XXXXXX X

Device Family
LatticeXP FPGA

Logic Capacity
3K LUTs = 3
6K LUTs = 6
10K LUTs = 10
15K LUTs = 15
20K LUTs = 20

Supply Voltage
C = 1.8V/2.5V/3.3V
E = 1.2V

Note: Parts dual marked per table below.

Grade
C = Commercial
I = Industrial

Package
T100 = 100-pin TQFP
T144 = 144-pin TQFP
Q208 = 208-pin PQFP
F256 = 256-ball fpBGA
F388 = 388-ball fpBGA
F484 = 484-ball fpBGA

TN100 = 100-pin Lead-free TQFP
TN144 = 144-pin Lead-free TQFP
QN208 = 208-pin Lead-free PQFP
FN256 = 256-ball Lead-free fpBGA
FN388 = 388-ball Lead-free fpBGA
FN484 = 484-ball Lead-free fpBGA

Speed
3 = Slowest
4
5 = Fastest

Ordering Information (Contact Factory for Specific Device Availability)

Note:þLatticeXP devices are dual marked. For example, the commercial speed grade LFXP10E-4F256C is also marked with industrial grade -3I (LFXP10E-3F256I). The commercial grade is one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade does not have industrial markings. The markings appear as follows:

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20C-3FN484C	340	1.8/2.5/3.3V	-3	fpBGA	484	COM	19.7K
LFXP20C-4FN484C	340	1.8/2.5/3.3V	-4	fpBGA	484	COM	19.7K
LFXP20C-5FN484C	340	1.8/2.5/3.3V	-5	fpBGA	484	COM	19.7K
LFXP20C-3FN388C	268	1.8/2.5/3.3V	-3	fpBGA	388	COM	19.7K
LFXP20C-4FN388C	268	1.8/2.5/3.3V	-4	fpBGA	388	COM	19.7K
LFXP20C-5FN388C	268	1.8/2.5/3.3V	-5	fpBGA	388	COM	19.7K
LFXP20C-3FN256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	19.7K
LFXP20C-4FN256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	19.7K
LFXP20C-5FN256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	19.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3E-3QN208C	136	1.2V	-3	PQFP	208	COM	3.1K
LFXP3E-4QN208C	136	1.2V	-4	PQFP	208	COM	3.1K
LFXP3E-5QN208C	136	1.2V	-5	PQFP	208	COM	3.1K
LFXP3E-3TN144C	100	1.2V	-3	TQFP	144	COM	3.1K
LFXP3E-4TN144C	100	1.2V	-4	TQFP	144	COM	3.1K
LFXP3E-5TN144C	100	1.2V	-5	TQFP	144	COM	3.1K
LFXP3E-3TN100C	62	1.2V	-3	TQFP	100	COM	3.1K
LFXP3E-4TN100C	62	1.2V	-4	TQFP	100	COM	3.1K
LFXP3E-5TN100C	62	1.2V	-5	TQFP	100	COM	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3FN256C	188	1.2V	-3	fpBGA	256	COM	5.8K
LFXP6E-4FN256C	188	1.2V	-4	fpBGA	256	COM	5.8K
LFXP6E-5FN256C	188	1.2V	-5	fpBGA	256	COM	5.8K
LFXP6E-3QN208C	142	1.2V	-3	PQFP	208	COM	5.8K
LFXP6E-4QN208C	142	1.2V	-4	PQFP	208	COM	5.8K
LFXP6E-5QN208C	142	1.2V	-5	PQFP	208	COM	5.8K
LFXP6E-3TN144C	100	1.2V	-3	TQFP	144	COM	5.8K
LFXP6E-4TN144C	100	1.2V	-4	TQFP	144	COM	5.8K
LFXP6E-5TN144C	100	1.2V	-5	TQFP	144	COM	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3FN388C	244	1.2V	-3	fpBGA	388	COM	9.7K
LFXP10E-4FN388C	244	1.2V	-4	fpBGA	388	COM	9.7K
LFXP10E-5FN388C	244	1.2V	-5	fpBGA	388	COM	9.7K
LFXP10E-3FN256C	188	1.2V	-3	fpBGA	256	COM	9.7K
LFXP10E-4FN256C	188	1.2V	-4	fpBGA	256	COM	9.7K
LFXP10E-5FN256C	188	1.2V	-5	fpBGA	256	COM	9.7K

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10C-3FN388I	244	1.8/2.5/3.3V	-3	fpBGA	388	IND	9.7K
LFXP10C-4FN388I	244	1.8/2.5/3.3V	-4	fpBGA	388	IND	9.7K
LFXP10C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	9.7K
LFXP10C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	9.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15C-3FN484I	300	1.8/2.5/3.3V	-3	fpBGA	484	IND	15.5K
LFXP15C-4FN484I	300	1.8/2.5/3.3V	-4	fpBGA	484	IND	15.5K
LFXP15C-3FN388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	15.5K
LFXP15C-4FN388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	15.5K
LFXP15C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	15.5K
LFXP15C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20C-3FN484I	340	1.8/2.5/3.3V	-3	fpBGA	484	IND	19.7K
LFXP20C-4FN484I	340	1.8/2.5/3.3V	-4	fpBGA	484	IND	19.7K
LFXP20C-3FN388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	19.7K
LFXP20C-4FN388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	19.7K
LFXP20C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	19.7K
LFXP20C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	19.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3E-3QN208I	136	1.2V	-3	PQFP	208	IND	3.1K
LFXP3E-4QN208I	136	1.2V	-4	PQFP	208	IND	3.1K
LFXP3E-3TN144I	100	1.2V	-3	TQFP	144	IND	3.1K
LFXP3E-4TN144I	100	1.2V	-4	TQFP	144	IND	3.1K
LFXP3E-3TN100I	62	1.2V	-3	TQFP	100	IND	3.1K
LFXP3E-4TN100I	62	1.2V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3FN256I	188	1.2V	-3	fpBGA	256	IND	5.8K
LFXP6E-4FN256I	188	1.2V	-4	fpBGA	256	IND	5.8K
LFXP6E-3QN208I	142	1.2V	-3	PQFP	208	IND	5.8K
LFXP6E-4QN208I	142	1.2V	-4	PQFP	208	IND	5.8K
LFXP6E-3TN144I	100	1.2V	-3	TQFP	144	IND	5.8K
LFXP6E-4TN144I	100	1.2V	-4	TQFP	144	IND	5.8K

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3FN388I	244	1.2V	-3	fpBGA	388	IND	9.7K
LFXP10E-4FN388I	244	1.2V	-4	fpBGA	388	IND	9.7K
LFXP10E-3FN256I	188	1.2V	-3	fpBGA	256	IND	9.7K
LFXP10E-4FN256I	188	1.2V	-4	fpBGA	256	IND	9.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3FN484I	300	1.2V	-3	fpBGA	484	IND	15.5K
LFXP15E-4FN484I	300	1.2V	-4	fpBGA	484	IND	15.5K
LFXP15E-3FN388I	268	1.2V	-3	fpBGA	388	IND	15.5K
LFXP15E-4FN388I	268	1.2V	-4	fpBGA	388	IND	15.5K
LFXP15E-3FN256I	188	1.2V	-3	fpBGA	256	IND	15.5K
LFXP15E-4FN256I	188	1.2V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3FN484I	340	1.2V	-3	fpBGA	484	IND	19.7K
LFXP20E-4FN484I	340	1.2V	-4	fpBGA	484	IND	19.7K
LFXP20E-3FN388I	268	1.2V	-3	fpBGA	388	IND	19.7K
LFXP20E-4FN388I	268	1.2V	-4	fpBGA	388	IND	19.7K
LFXP20E-3FN256I	188	1.2V	-3	fpBGA	256	IND	19.7K
LFXP20E-4FN256I	188	1.2V	-4	fpBGA	256	IND	19.7K